



SOT617-2

HVQFN32: plastic thermal enhanced very thin quad flat package; no leads; 32 terminals; 0.5 mm pitch, 5 mm x 5 mm x 0.85 mm body

12 July 2021

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN32
Package type industry code	HVQFN32
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
JEDEC package outline code	MO-220
Mounting method type	S (surface mount)
Issue date	02-05-2003
Manufacturer package code	SOT617

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	4.9	5	5.1	mm
package width	4.9	5	5.1	mm
seated height	-	0.85	1	mm
package height	-	0.85	-	mm
actual quantity of termination	-	32	-	

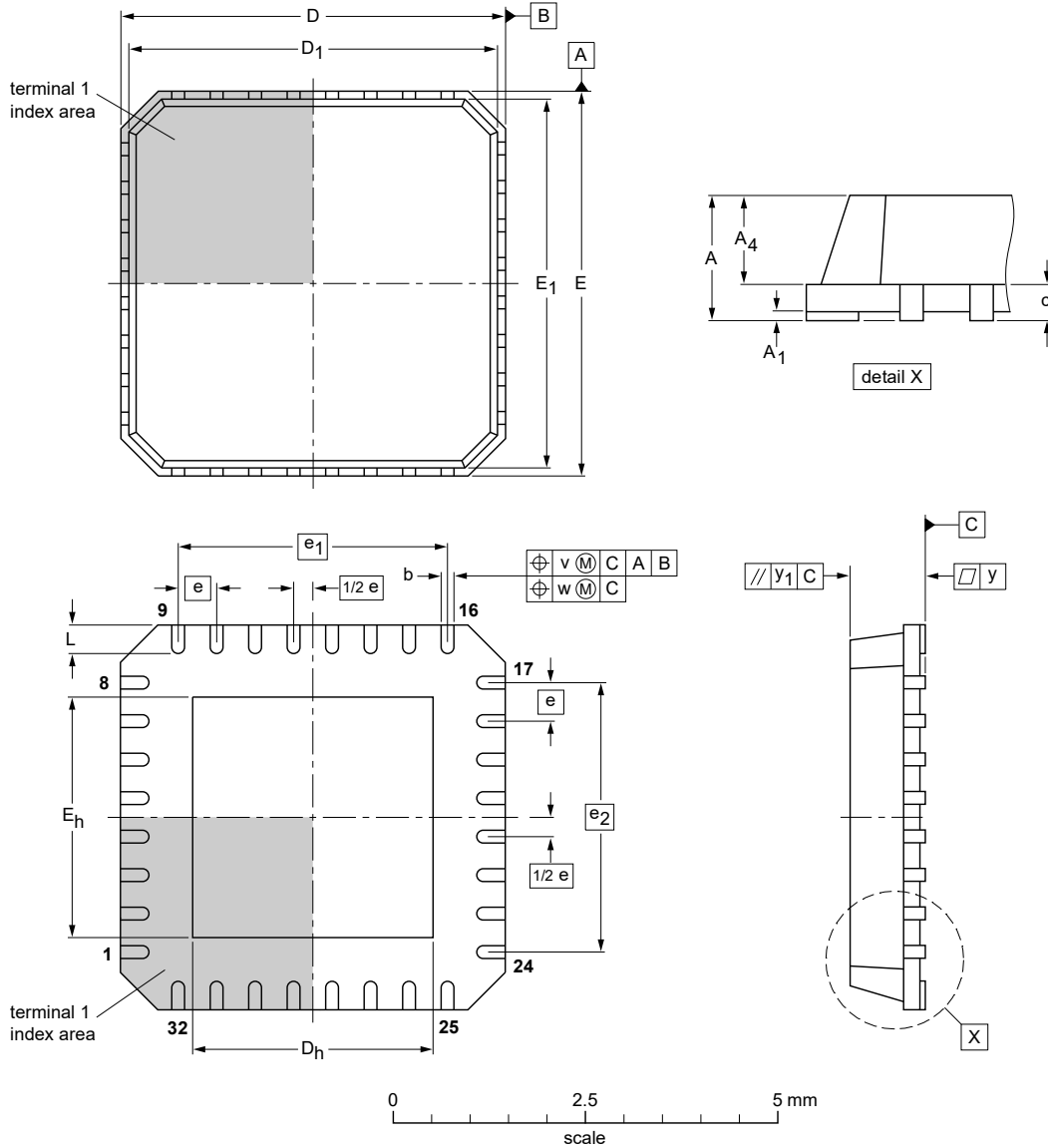


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2 Package outline

HVQFN32: plastic thermal enhanced very thin quad flat package; no leads; 32 terminals; body 5 x 5 x 0.85 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₄	b	c	D	D ₁	D _h	E	E ₁	E _h	e	e ₁	e ₂	L	v	w	y	y ₁
mm	1	0.05 0.00	0.80 0.65	0.30 0.18	0.2	5.1 4.9	4.8 4.7	3.4 3.2	5.1 4.9	4.8 4.7	3.4 3.2	0.5	3.5	3.5	0.5 0.3	0.1	0.05	0.05	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT617-2	---	MO-220	---			03-04-22 03-05-02

Figure 1. Package outline HVQFN32 (SOT617-2)

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3 Soldering

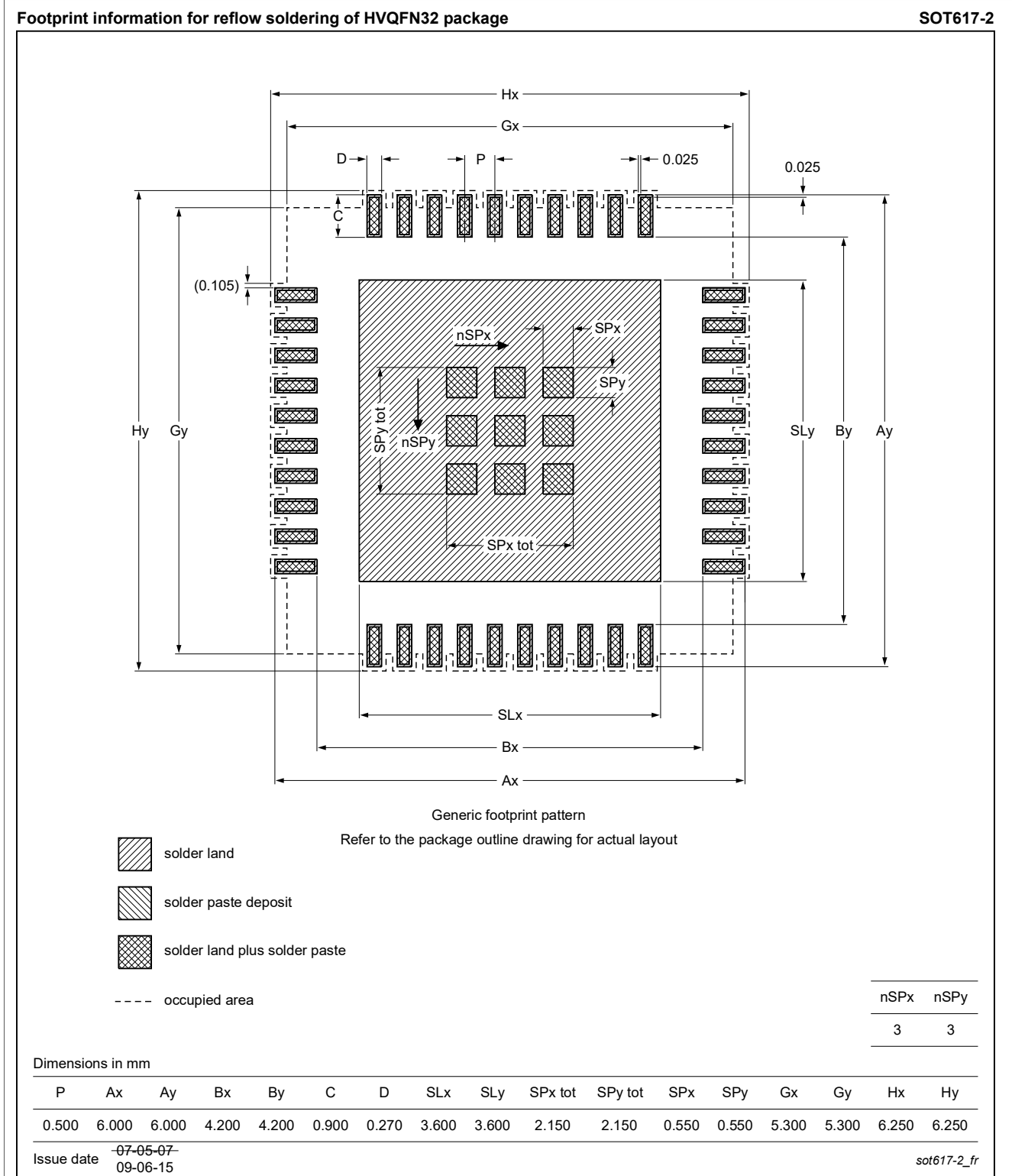


Figure 2. Reflow soldering footprint for HVQFN32 (SOT617-2)

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4 Legal information

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